Avant GD 株式会社

AVANT GD Corporation, LTD

Wafer Surface Defect Inspection System for Compound Semiconductor Material

~ LSR8528 for SiC
~ LSR8728 for GaN
~ LSR8428 for GaAs & InP

LSR 8528

Specification

Wafer Size	4”, 6”, 8”
Wafer Thickness	300μm~1500μm
DF Inspection Channel	60nm PSL equivalent on Si
PL Inspection Channel	355nm/320nm laser option NUV/VIS/NIR PL channel option
Defect Algorithm	Multi-channel defect extraction User-defined classification rules
Offset Between Channels	< 30 μm
Defect Coordinate Accuracy	<50 μm
Throughput in Standard Sensitivity Mode	● 22 WPH 6 inch in surface mode ● 16 WPH 6 inch in surface mode and PL mode ● 13 WPH 8 inch in surface mode ● 12 WPH 8 inch in surface mode and PL mode

- This tool is **China's first laser scanning inspection system** designed specifically for Third-generation semiconductor defect detection equipment.
- It is **different from AOI equipment** and directly **competes with the K company 85xx**.
- Suitable for transparent and opaque substrates, such as SiC, GaN, Glass, Si, GaAs, InP, LT, LN, POI and other composite substrates